



**BOARD LEVEL COOLING - Thin Fin 3410**

Thin Fin 3410 is a series of thin-fin board level heat sinks designed to cool PCI/AGP chip set devices. Representative image only.

**ORDERING INFORMATION**

Part Number	Device Type
341800F00000G	PCI/AGP Chip Sets
341900F00000G	PCI/AGP Chip Sets

**HEAT SINK DETAILS**

Property	Details
Material	Copper
Finish	Polyvinylflouride
Device Attachment Options	Adhesive
Thermal Interface Material	Adhesive

Property	Details
Heat Sink Width (mm)	76.20
Heat Sink Length (mm)	19.1
Heat Sink Height (mm)	0.33
Heat Sink Mounting Direction	Horizontal, Vertical



**MECHANICAL & PERFORMANCE**

Drawing dimensions are shown in mm, (in)

Part Number	"L" Dim
341800F00000G	19.10
341900F00000G	25.40

